For over 20 years Semiconductor Equipment Corporation has set the standard for high quality semiconductor Dicing Tape. We inventory a variety of tapes which are manufactured specifically for semiconductor wafer dicing and for ceramic hybrid substrate sawing. These tapes are also useful for surface protection and many other applications that require an adhesive tape with relatively low adhesion, no adhesive transfer, and the ability to stretch without tearing.
There is a Semiconductor Equipment Tape that is Perfect for Your Application.

Semiconductor Equipment Corporation's Wafer Dicing Tape is a flexible PVC with synthetic acrylic adhesive bonded to one side. It is tough, has high tear strength and elongation. It is used extensively for Wafer Sawing, Scribing, Expanding. These tapes are available in rolls suitable for all automatic and manual wafer mounting systems where the wafers are being mounted onto tape and film frames.

**Low Tack-Blue**

Specific Uses - Sawing wafers with larger die sizes. Adhesion is high enough to hold die firmly during sawing, but low enough for die to be easily removed by die bonders or pick & place equipment.

**Medium Tack-Blue**

Specific Uses - Sawing silicon wafers with smaller die sizes. Adhesion level is slightly greater than Low Tack-Blue to more firmly hold die to tape but low enough to easily remove die in the next operation.

**High Tack-Black**

Specific Uses - Sawing ceramic and other hard-to-cut material or when slightly more adhesion is required. This tape is thicker than other tapes to allow deeper dicing saw penetration.

**Low Tack-Clear**

Specific Uses - Sawing silicon wafers where a thicker tape than Low Tack-Blue is required with the same adhesion level.

**Squares**

Specific Uses - A handy way to dispense tape for users without tape handling equipment. Also ideal for use with interlocking rings. Available in Low & Medium Tack Blue, High Tack-Black and Low Tack-Clear.

**Non-Adhesive Clear**

Four Mil thick. Available in squares only. This is a flexible polyvinyl chloride with excellent clarity. It is tough, has high tear strength and elongation. Available on non-contaminating backing paper, it is used extensively for Wafer Fracturing, Expanding and Surface Protection. Wafers or die are mounted to the plastic by applying low 65°C heat.

Along with our tape, Semiconductor Equipment Corporation produces an entire family of tape handling equipment to enable the applications involving this tape to be completed quickly, accurately and efficiently.
# Semiconductor Equipment Corporation

## Dicing Tape

For almost 30 years Semiconductor Equipment Corporation has set the standard for high quality dicing tape.

Tapes are selected for your application based on die size and blade thickness. Small die and hard to cut materials require higher tackiness, while larger die call for lower tackiness. Thicker blades require thicker tape.

For additional information, please contact our Tape Specialist at (805) 529-2293 or sales@semicorp.com.

### Standard Dicing Tape
SEC’s most popular economical electronic grade dicing tape.

- **Blue Low Tack Rolls** (P/N 18733)  
  Thickness 75 um / .003”  
  Length 200 M / 660’

- **Blue Medium Tack Rolls** (P/N 16074)  
  Thickness 100 um / .004”  
  Length 200 M / 660’

- **Thick Clear Low Rolls** (P/N 24353)  
  Thickness 120 um / .0047”  
  Length 100 M / 330’

- **Clear Low Tack Rolls** (P/N 19161)  
  Thickness 100 um / .004”  
  Length 100 M & 200 M / 330’ & 660’

- **Squares**  
  All the above tapes are available in precut squares mounted on release paper. Standard sizes are 5.75” and 7.50”. Custom sizes are available.

- **Inkjet Cover Tape**  
  Blue tape in widths and adhesion levels designed for Inkjet cover tape.

- **Revalpha Heat Release**  
  Excellent for high temperature applications. Available in single and double sided. Polyester film, acrylic adhesive, PET Liner.

### UV Curable Dicing Tape
A very high adhesive strength secures wafers firmly during dicing, while allowing for easy removal after exposure.

- **P/N 24339 DU-300** Super High Tack, PVC, 85 um thick  
  our most popular UV tape

- **P/N 24351 NBD-5170K Super High Tack 170 um thick**  
  for dicing BGA & ceramic

- **P/N 25551 DU-2187G Super High Tack 88 um thick**  
  for metalized wafers

- **P/N 25587 NBD-3190K 193 um thick** for glass dicing

- **P/N 25822 NBD-7163K 160 um thick** for green package

- **P/N 25862 WS-02T Medium Tack 88 um thick**

- **P/N 26115 DU-2285KS Low Tack 85um thick Anti-ESD**

- **P/N 26120 DU-2385KS Low Tack 85um thick Anti-ESD**  
  For metalized wafers

### High Purity Pressure Sensitive Expandable Tape with Liner
Low ionic impurities and adhesion stability make this the perfect tape for your clean room application.

- **P/N 24208 V8LR** Low Tack 75 um thick medium thick size

- **P/N 24205 V8TR** Low Tack 75 um thick stable over time

- **P/N 25211 V95R** Medium Tack, 70 um thick most popular

- **P/N 24211 VD15R** High Tack 145 um thick small chip size

### Backgrinding Tape
Low contamination, consistent thickness accuracy, high acid resistance and effective protection during wet processes. UV and Anti-ESD products available.

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### Aquabond Adhesives
A family of unique, water soluble adhesives to mount items that require extra firm mounting, for dicing, grinding and polishing.